

TOSHIBA**TC74VCX16721FT**

TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

TC74VCX16721FT
**LOW-VOLTAGE 20-BIT D-TYPE FLIP-FLOP
WITH 3.6 V TOLERANT INPUTS AND OUTPUTS**

The TC74VCX16721FT is a high performance CMOS 20-bit D-TYPE FLIP-FLOP. Designed for use in 1.8, 2.5 or 3.3 Volt systems, it achieves high speed operation while maintaining the CMOS low power dissipation.

It is also designed with over voltage tolerant inputs and outputs up to 3.6 V.

The TC74VCX16721FT is edge-triggered D-type flip-flop with qualified clock storage. On the positive transition of the clock (CK) input, the device provides true data at the Q outputs if the clock-enable (CKEN) input is low. If CKEN is high, no data is stored.

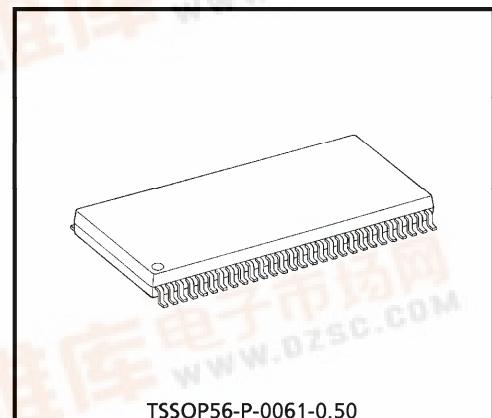
When the \overline{OE} input is high, the outputs are in a high impedance state. This device is designed to be used with 3-state memory address drivers, etc.

All inputs are equipped with protection circuits against static discharge.

FEATURES

- Low Voltage Operation : $V_{CC} = 1.8 \sim 3.6$ V
- High Speed Operation : $t_{pd} = 3.5$ ns (max) at $V_{CC} = 3.0 \sim 3.6$ V
 : $t_{pd} = 4.4$ ns (max) at $V_{CC} = 2.3 \sim 2.7$ V
 : $t_{pd} = 8.8$ ns (max) at $V_{CC} = 1.8$ V
- 3.6V Tolerant inputs and outputs.
- Output Current : $I_{OH}/I_{OL} = \pm 24$ mA (min) at $V_{CC} = 3.0$ V
 : $I_{OH}/I_{OL} = \pm 18$ mA (min) at $V_{CC} = 2.3$ V
 : $I_{OH}/I_{OL} = \pm 6$ mA (min) at $V_{CC} = 1.8$ V
- Latch-up Performance : ± 300 mA
- ESD Performance : Human Body Model $> \pm 2000$ V
 : Machine Model $> \pm 200$ V
- Package : TSSOP
 (Thin Shrink Small Outline Package)
- Power Down Protection is provided on all inputs and outputs.
- Supports live insertion/withdrawal (Note 1)

(Note 1) : To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.



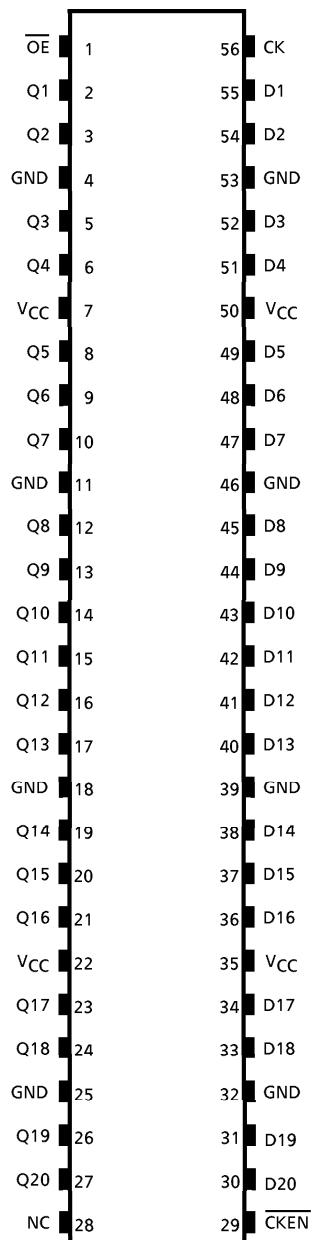
TSSOP56-P-0061-0.50

Weight : 0.25 g (Typ.)

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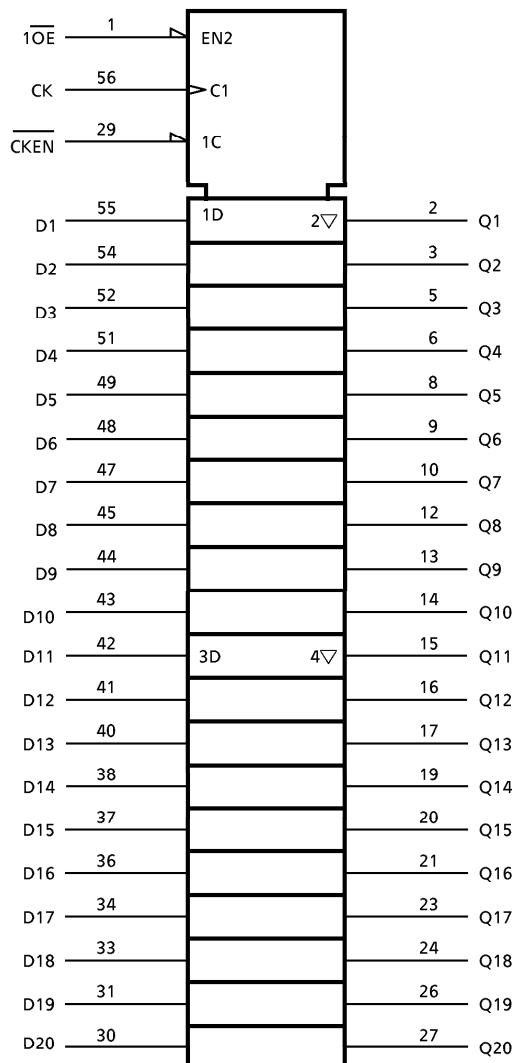
980910EBA2

PIN ASSIGNMENT



(TOP VIEW)

SYMBOL



980910EBA2'

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TRUTH TABLE (each flip flop)

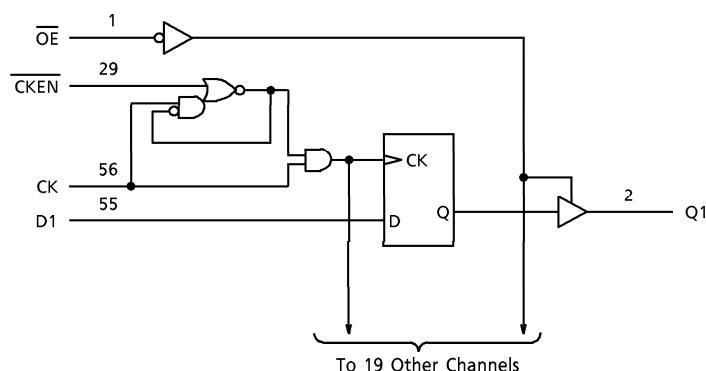
INPUTS				OUTPUTS Q
OE	CKEN	CK	D	
L	H	X	X	Q0
L	L	↑	H	H
L	L	↑	L	L
L	L	↓	X	Q0
H	X	X	X	Z

X : Don't Care

Z : High impedance

Qn : No change

SYSTEM DIAGRAM



MAXIMUM RATINGS

PARAMETER	SYMBOL	RATING	UNIT
Power Supply Voltage	V _{CC}	-0.5~4.6	V
DC Input Voltage	V _{IN}	-0.5~4.6	V
DC Output Voltage	V _{OUT}	-0.5~4.6 (Note 1)	V
		-0.5~V _{CC} + 0.5 (Note 2)	
Input Diode Current	I _{IK}	-50	mA
Output Diode Current	I _{OK}	± 50 (Note 3)	mA
DC Output Current	I _{OUT}	± 50	mA
Power Dissipation	P _D	400	mW
DC V _{CC} / Ground Current Per Supply Pin	I _{CC} / I _{GND}	± 100	mA
Storage Temperature	T _{stg}	-65~150	°C

(Note 1) : Off-State

(Note 2) : High or Low State. I_{OUT} absolute maximum rating must be observed.(Note 3) : V_{OUT} < GND, V_{OUT} > V_{CC}

RECOMMENDED OPERATING RANGE

PARAMETER	SYMBOL	RATING	UNIT
Supply Voltage	V_{CC}	1.8~3.6	V
		1.2~3.6 (Note 4)	
Input Voltage	V_{IN}	-0.3~3.6	V
Output Voltage	V_{OUT}	0~3.6 (Note 5)	V
		0~ V_{CC} (Note 6)	
Output Current	I_{OH}/I_{OL}	± 24 (Note 7)	mA
		± 18 (Note 8)	
		± 6 (Note 9)	
Operating Temperature	T_{opr}	-40~85	°C
Input Rise And Fall Time	dt/dv	0~10 (Note 10)	ns/V

(Note 4) : Data Retention Only

(Note 5) : Off-State

(Note 6) : High or Low State

(Note 7) : $V_{CC} = 3.0\sim 3.6$ V(Note 8) : $V_{CC} = 2.3\sim 2.7$ V(Note 9) : $V_{CC} = 1.8$ V(Note 10) : $V_{IN} = 0.8\sim 2.0$ V, $V_{CC} = 3.0$ V

ELECTRICAL CHARACTERISTICS

DC characteristics ($T_a = -40\sim 85^\circ C$, 2.7 V $< V_{CC} \leq 3.6$ V)

PARAMETER		SYMBOL	TEST CONDITION		V_{CC} (V)	MIN	MAX	UNIT	
Input Voltage	"H" Level	V_{IH}	V_{IN} = V_{IH} or V_{IL}	$I_{OH} = -100 \mu A$	2.7~3.6	2.0	—	V	
	"L" Level	V_{IL}		$I_{OH} = -12$ mA	2.7~3.6	—	0.8		
Output Voltage	"H" Level	V_{OH}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -18$ mA	3.0	2.4	—	V	
				$I_{OH} = -24$ mA	3.0	2.2	—		
				$I_{OL} = 100 \mu A$	2.7~3.6	—	0.2		
				$I_{OL} = 12$ mA	2.7	—	0.4		
	"L" Level	V_{OL}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OL} = 18$ mA	3.0	—	0.4	V	
				$I_{OL} = 24$ mA	3.0	—	0.55		
Input Leakage Current	I_{IN}	$V_{IN} = 0\sim 3.6$ V		2.7~3.6	—	± 5.0	μA		
3-State Output Off-State Current	I_{OZ}	$V_{IN} = V_{IH}$ or V_{IL}		2.7~3.6	—	± 10.0	μA		
Power Off Leakage Current	I_{OFF}	$V_{IN}, V_{OUT} = 0\sim 3.6$ V		0	—	10.0	μA		
Quiescent Supply Current	I_{CC}	$V_{IN} = V_{CC}$ or GND		2.7~3.6	—	20.0	μA		
		$V_{CC} \leq (V_{IN}, V_{OUT}) \leq 3.6$ V		2.7~3.6	—	± 20.0			
Increase In I_{CC} Per Input	ΔI_{CC}	$V_{IH} = V_{CC} - 0.6$ V		2.7~3.6	—	750	μA		

ELECTRICAL CHARACTERISTICSDC characteristics ($T_a = -40\text{--}85^\circ\text{C}$, $2.3\text{ V} \leq V_{CC} \leq 2.7\text{ V}$)

PARAMETER		SYMBOL	TEST CONDITION		V_{CC} (V)	MIN.	MAX.	UNIT	
Input Voltage	"H" Level	V_{IH}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -100\text{ }\mu\text{A}$	2.3~2.7	1.6	—	V	
	"L" Level	V_{IL}		$I_{OH} = -6\text{ mA}$	2.3~2.7	—	0.7		
Output Voltage	"H" Level	V_{OH}		$I_{OH} = -12\text{ mA}$	2.3	2.0	—	V	
				$I_{OH} = -18\text{ mA}$	2.3	1.8	—		
				$I_{OL} = 100\text{ }\mu\text{A}$	2.3~2.7	—	0.2		
				$I_{OL} = 12\text{ mA}$	2.3	—	0.4		
	"L" Level	V_{OL}		$I_{OL} = 18\text{ mA}$	2.3	—	0.6		
				I_{IN}	$V_{IN} = 0\text{--}3.6\text{ V}$	2.3~2.7	—	± 5.0	
				I_{OZ}	$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = 0\text{--}3.6\text{ V}$	2.3~2.7	—	± 10.0	
				I_{OFF}	$V_{IN}, V_{OUT} = 0\text{--}3.6\text{ V}$	0	—	10.0	
Quiescent Supply Current		I_{CC}	$V_{IN} = V_{CC}$ or GND		2.3~2.7	—	20.0	μA	
			$V_{CC} \leq (V_{IN}, V_{OUT}) \leq 3.6\text{ V}$		2.3~2.7	—	± 20.0		

ELECTRICAL CHARACTERISTICSDC characteristics ($T_a = -40\text{--}85^\circ\text{C}$, $1.8\text{ V} \leq V_{CC} < 2.3\text{ V}$)

PARAMETER		SYMBOL	TEST CONDITION		V_{CC} (V)	MIN	MAX	UNIT	
Input Voltage	"H" Level	V_{IH}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -100\text{ }\mu\text{A}$	1.8~2.3	$0.7 \times V_{CC}$	—	V	
	"L" Level	V_{IL}		$I_{OH} = -6\text{ mA}$	1.8~2.3	—	$0.2 \times V_{CC}$		
Output Voltage	"H" Level	V_{OH}		$I_{OH} = -12\text{ mA}$	1.8	$V_{CC} - 0.2$	—	V	
				$I_{OH} = -6\text{ mA}$	1.8	1.4	—		
	"L" Level	V_{OL}		$I_{OL} = 100\text{ }\mu\text{A}$	1.8	—	0.2		
				$I_{OL} = 6\text{ mA}$	1.8	—	0.3		
Input Leakage Current		I_{IN}		$V_{IN} = 0\text{--}3.6\text{ V}$	1.8	—	± 5.0	μA	
3-State Output Off-State Current		I_{OZ}		$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = 0\text{--}3.6\text{ V}$	1.8	—	± 10.0	μA	
Power Off Leakage Current		I_{OFF}		$V_{IN}, V_{OUT} = 0\text{--}3.6\text{ V}$	0	—	10.0	μA	
Quiescent Supply Current		I_{CC}	$V_{IN} = V_{CC}$ or GND		1.8	—	20.0	μA	
			$V_{CC} \leq (V_{IN}, V_{OUT}) \leq 3.6\text{ V}$		1.8	—	± 20.0		

AC characteristics ($T_a = -40\sim85^\circ C$, Input $t_r = t_f = 2.0 \text{ ns}$, $C_L = 30 \text{ pF}$, $R_L = 500 \Omega$)

PARAMETER	SYMBOL	TEST CONDITION	$V_{CC} (\text{V})$	MIN	MAX	UNIT
			1.8	100	—	
Maximum Clock Frequency	f_{MAX}	(Fig.1, 2)	2.5 ± 0.2	200	—	MHz
			3.3 ± 0.3	250	—	
			1.8	1.5	8.8	
Propagation Delay Time (CK-Q)	t_{pLH} t_{pHL}	(Fig.1, 2)	2.5 ± 0.2	1.0	4.4	ns
			3.3 ± 0.3	0.8	3.5	
			1.8	1.5	9.8	
3-State Output Enable Time	t_{pZL} t_{pZH}	(Fig.1, 3)	2.5 ± 0.2	1.0	4.9	ns
			3.3 ± 0.3	0.8	3.8	
			1.8	1.5	7.6	
3-State Output Disable Time	t_{pLZ} t_{pHZ}	(Fig.1, 3)	2.5 ± 0.2	1.0	4.2	ns
			3.3 ± 0.3	0.8	3.7	
			1.8	4.0	—	
Minimum Pulse Width (CK)	$t_w (\text{H})$ $t_w (\text{L})$	(Fig.1, 2)	2.5 ± 0.2	1.5	—	ns
			3.3 ± 0.3	1.5	—	
			1.8	2.5	—	
Minimum Set-up Time (D, CKEN)	t_s	(Fig.1, 2, 4)	2.5 ± 0.2	1.5	—	ns
			3.3 ± 0.3	1.5	—	
			1.8	1.0	—	
Minimum Hold Time (D, CKEN)	t_h	(Fig.1, 2, 4)	2.5 ± 0.2	1.0	—	ns
			3.3 ± 0.3	1.0	—	
			1.8	—	0.5	
Output to Output Skew	t_{osLH} t_{osHL}	(Note 11)	2.5 ± 0.2	—	0.5	ns
			3.3 ± 0.3	—	0.5	
			1.8	—	0.5	

For $C_L = 50 \text{ pF}$, add approximately 300 ps to the AC maximum specification.

(Note 11) : Parameter guaranteed by design.

$$(t_{osLH} = |t_{pLHm} - t_{pLHn}|, t_{osHL} = |t_{pHLm} - t_{pHLn}|)$$

Dynamic switching characteristics ($T_a = 25^\circ\text{C}$, Input $t_r = t_f = 2.0 \text{ ns}$, $C_L = 30 \text{ pF}$)

PARAMETER	SYMBOL	TEST CONDITION	$V_{CC} (\text{V})$	TYP.	UNIT
Quiet Output Maximum Dynamic V_{OL}	V_{OLP}	$V_{IH} = 1.8 \text{ V}, V_{IL} = 0 \text{ V}$ (Note 12)	1.8	0.25	V
		$V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$ (Note 12)	2.5	0.6	
		$V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ (Note 12)	3.3	0.8	
Quiet Output Minimum Dynamic V_{OL}	V_{OLV}	$V_{IH} = 1.8 \text{ V}, V_{IL} = 0 \text{ V}$ (Note 12)	1.8	-0.25	V
		$V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$ (Note 12)	2.5	-0.6	
		$V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ (Note 12)	3.3	-0.8	
Quiet Output Minimum Dynamic V_{OH}	V_{OHV}	$V_{IH} = 1.8 \text{ V}, V_{IL} = 0 \text{ V}$ (Note 12)	1.8	1.5	V
		$V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$ (Note 12)	2.5	1.9	
		$V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ (Note 12)	3.3	2.2	

(Note 12) : Parameter guaranteed by design.

Capacitive characteristics ($T_a = 25^\circ\text{C}$)

PARAMETER	SYMBOL	TEST CONDITION	$V_{CC} (\text{V})$	TYP.	UNIT
Input Capacitance	C_{IN}		1.8, 2.5, 3.3	6	pF
Output Capacitance	C_O		1.8, 2.5, 3.3	7	pF
Power Dissipation Capacitance	C_{PD}	$f_{IN} = 10 \text{ MHz}$ (Note 13)	1.8, 2.5, 3.3	60	pF

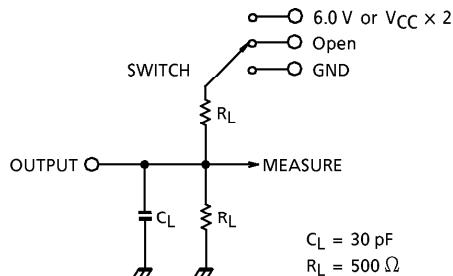
(Note 13) : C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

$$I_{CC (\text{opr.})} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 20 \text{ (per bit)}$$

TEST CIRCUIT

Fig.1



PARAMETER	SWITCH
t_{pLH}, t_{pHL}	Open
t_{pLZ}, t_{pZL}	$6.0 \text{ V} @ V_{CC} = 3.3 \pm 0.3 \text{ V}$ $V_{CC} \times 2 @ V_{CC} = 2.5 \pm 0.2 \text{ V}$ $@ V_{CC} = 1.8 \text{ V}$
t_{pHZ}, t_{pZH}	GND

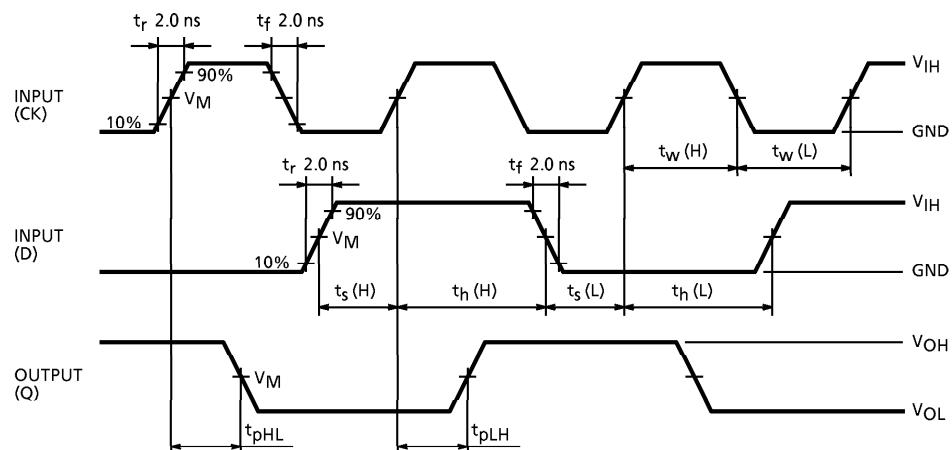
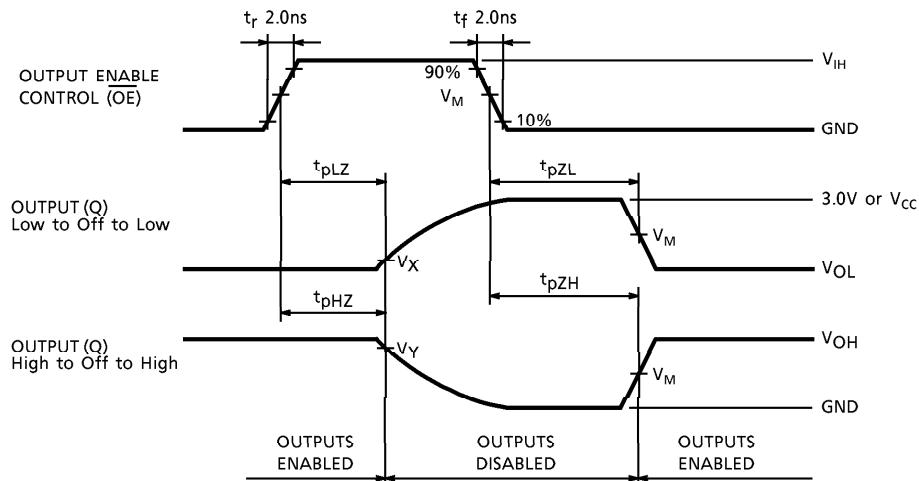
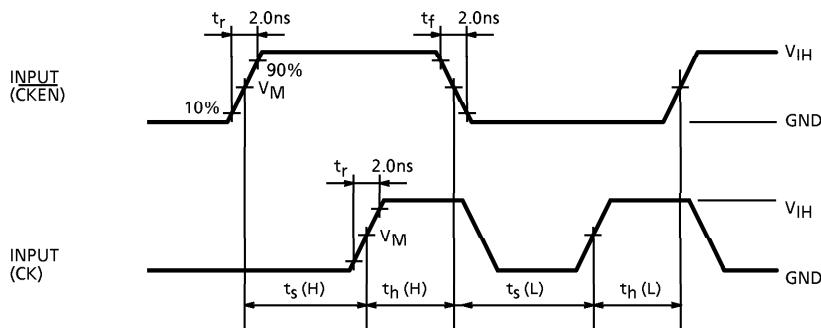
AC WAVEFORMFig.2 $t_{pLH}, t_{pHL}, t_w, t_s, t_h$ 

Fig.3 t_{PLZ} , t_{PHZ} , t_{PZL} , t_{PZH} 

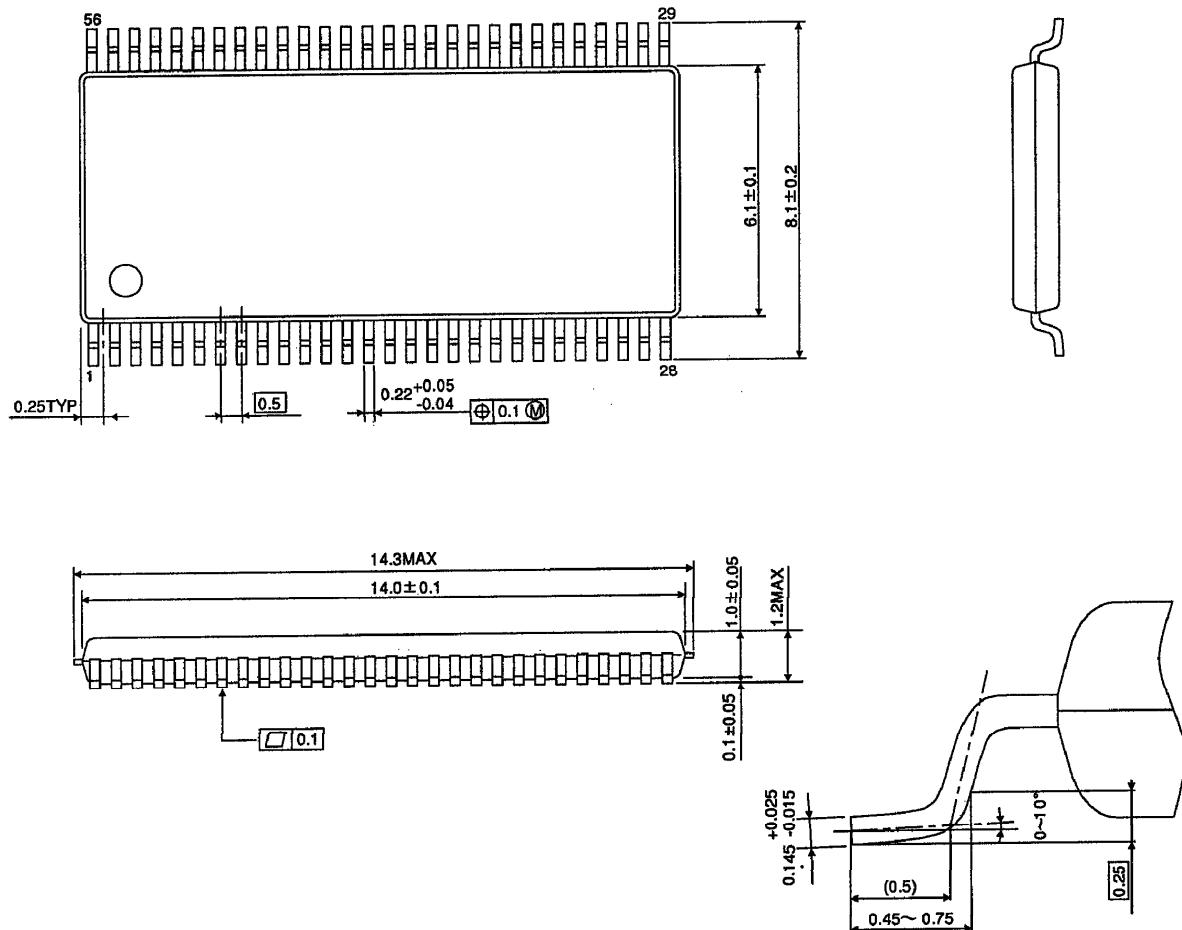
SYMBOL	V_{CC}		
	$3.3 \pm 0.3 V$	$2.5 \pm 0.2 V$	$1.8 V$
V_{IH}	2.7 V	V_{CC}	V_{CC}
V_M	1.5 V	$V_{CC} / 2$	$V_{CC} / 2$
V_X	$V_{OL} + 0.3 V$	$V_{OL} + 0.15 V$	$V_{OL} + 0.15 V$
V_Y	$V_{OH} - 0.3 V$	$V_{OH} - 0.15 V$	$V_{OH} - 0.15 V$

Fig.4 t_s , t_h 

PACKAGE DIMENSIONS

TSSOP56-P-0061-0.50

Unit : mm



Weight : 0.25 g (Typ.)